QUESTAR PRODUCTS
INTERNATIONAL, Inc.

Q7700 Automatic Gold Ball Bonder

Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements

Specifications*

Standard Features – Hardware

4” x 4” Bond Area
Programmable Temperature Controller
Programmable U/S Generator
Solid State Vision System
Pattern Recognition System
Flat Panel Monitor
Wireless Mouse
Stereo Zoom 4 Microscope
Galil Motion Control System
Windows XP™ OS
Programmable Temperature Controller
Fiber Optic Light Source

Specifications

Gold Wire
Size Range
0.0008” – 0.002” (20 – 51 microns)
Maximum Wires per Device
Unlimited

Bonding Speed per Wire
450 ms pending application

XY Table
Resolution
± 0.0000625” (1.6 microns)
Bonding Pitch
± 0.00275” (69.9 microns)

Standard Features – Software

Point and Click Bond Targeting
Simple, Intuitive Programming
Easy Bond Process Editing
Extensive Program Storage
Bond Parameter Library
Unlimited Wire Program Storage
Program Wire Groups for Multi Device,
High Wire Count Hybrids
Ball / Stud Bumping and Coining
Security Bond

Options

Custom Wire Profiles
High Frequency USG / Transducer
Heated Adjustable Workholder

Accessories

Ethernet Adapter for Networking Bonders
Additional Fiber Optic Light Source

Miscellaneous

Remote Diagnostics Capability
CE Mark

Facilities

Electric
120 VAC, 50/60 Hz, 20A (7A typical)
N2 or clean, dry air
Vacuum / Air as required for workholder

Dimension/Weight

Height:	72” (183 cm)
Width:	39” (99 cm)
Depth:	34.5” (88) cm)
Table Height:	40” (102 cm)
Weight:	600 pounds (273 Kg)
Crated Weight:	750 pounds (341 Kg)

* Subject to Change

01/01/11

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